



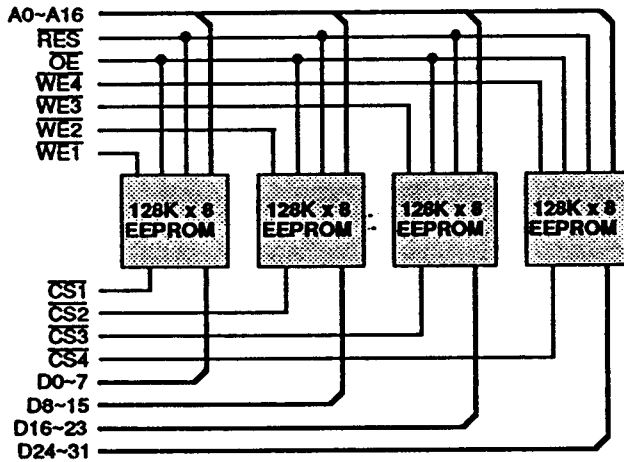
Mosaic Semiconductor Inc.

4,194,304 bit MNOS High Speed EEPROM

Features

- Fast Access Time of 120/150/200 ns.
- 66 PGA FR4 Epoxy Substrate.
- User Configurable as: 8 / 16 / 32 bit wide output.
- Operating Power @ 1MHz: 100 / 180 / 330 mW (max).
- Low Power Standby 400 μ W (max).
- Single Byte and Page Write (128 Bytes) operation.
- Software and Hardware Data Protection.
- RES Data Protection.
- DATA Polling Indication of End of Write.
- 10^5 Write/Erase Cycles in Page Mode.
- 10 Year Data Retention Time.

Block Diagram



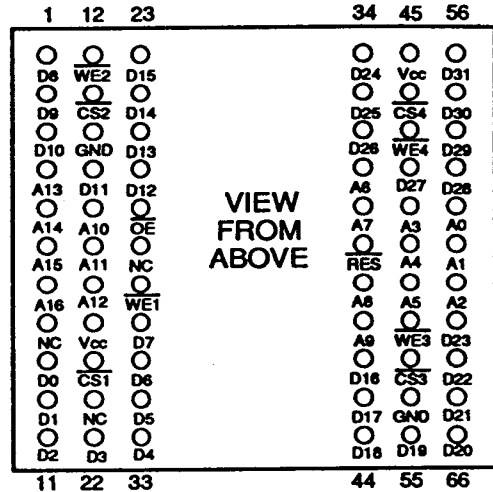
128Kx 32 EEPROM MODULE

PUMA 3E4000X-12/15/20

Issue 1.1 : September 1993

ADVANCE PRODUCT INFORMATION

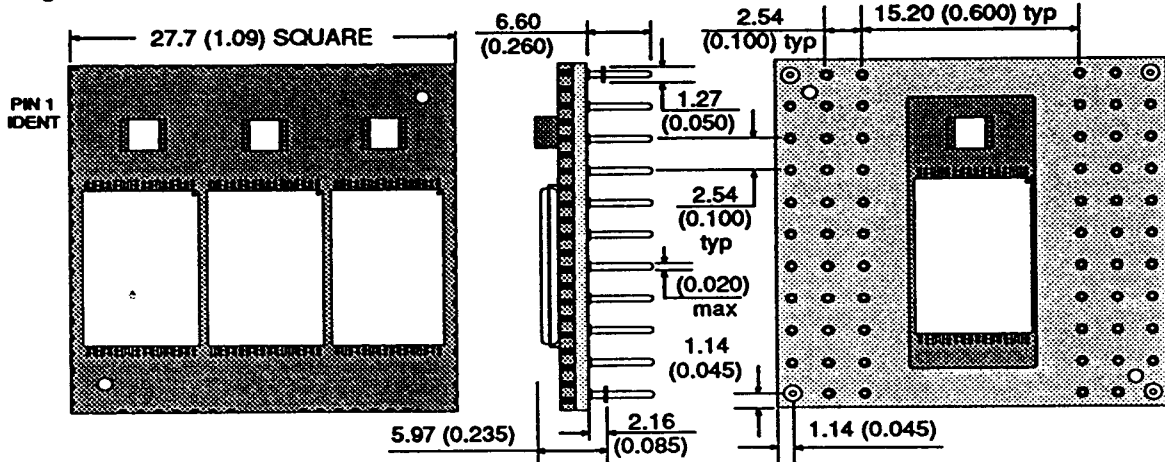
Pin Definition



Pin Functions

- A0-16 Address Inputs
- D0-31 Data Inputs/Outputs
- CS1-4 Chip Select
- OE Output Enable
- WE1-4 Write Enable
- RES Reset
- V_{cc} Power (+5V)
- GND Ground

Package Details Dimensions in mm (inches). All dimensions maximum unless otherwise stated.



Absolute Maximum Ratings ⁽¹⁾

Operating Temperature	T_{OPR}	-55 to +125	°C
Storage Temperature	T_{STG}	-65 to +150	°C
Input voltages (including N.C. pins) with Respect to GND ⁽²⁾	V_{IN}	-0.5 to +7.0	V
Supply Voltage with respect to GND	V_{CC}	-0.6 to +7.0	V

Notes : (1) Stresses above those listed may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

(2) May be -3.0V for pulse width of less than 50 ns.

Recommended Operating Conditions

		<i>min</i>	<i>typ</i>	<i>max</i>	
DC Power Supply Voltage	V_{CC}	4.5	5.0	5.5	V
Input Low Voltage	V_L	-0.3	-	0.8	V
Input High Voltage	V_H	2.2	-	$V_{CC}+1.0$	V
Operating Temp Range	T_A	0	-	70	°C
	T_{AI}	-40	-	85	°C (I Suffix)-15 and -20ns only

DC Electrical Characteristics ($T_A=0^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{CC}=5\text{V} \pm 10\%$)

Parameter	Symbol	Test Condition	<i>min</i>	<i>max</i>	Unit
Input Leakage Current	$\overline{CS1}\sim\overline{4}$, $\overline{WE1}\sim\overline{4}$	I_{LH} $V_{IN} = \text{GND to } V_{CC}$	-2	2	μA
	\overline{RES}	I_{L2} $V_{IN} = \text{GND to } V_{CC}$	-	100	μA
	Other Inputs	I_{L3} $V_{IN} = \text{GND to } V_{CC}$	-8	8	μA
Output Leakage Current	32 bit	I_{LO} $V_{IN} = \text{GND to } V_{CC}$, $\overline{CS}^{(1)}=V_H$	-2	2	μA
Operating Supply Current	32 bit	I_{CC32} $\overline{CS}^{(1)}=\overline{OE}=V_L$, $\overline{WE}^{(1)}=V_H$, $I_{OUT}=0\text{mA}$, $f=5\text{MHz}^{(2)}$	-	200	mA
	16 bit	I_{CC16} As above	-	106	mA
	8 bit	I_{CC8} As above	-	59	mA
Standby Supply Current	TTL levels	I_{SB1} $\overline{CS}^{(1)} = V_H$, $I_{IO} = 0\text{mA}$, Other Inputs = V_H	-	12	mA
	CMOS levels	I_{SB2} $\overline{CS}^{(1)} = V_{CC}-0.3\text{V}$, $I_{IO} = 0\text{mA}$, Other Inputs = V_{CC}	-	2	mA
Output Low Voltage	V_{OL}	$I_{OL} = 2.1\text{mA}$	-	0.4	V
Output High Voltage	V_{OH}	$I_{OH} = -400\mu\text{A}$	2.4	-	V

Notes (1) \overline{CS} and \overline{WE} above are accessed through $\overline{CS1}\sim\overline{4}$ and $\overline{WE1}\sim\overline{4}$ respectively. These inputs must be operated simultaneously for 32 bit operation, in pairs in 16 bit mode and singly for 8 bit mode.

(2) At an operating frequency of 1MHz, the 32 / 16 / 8 bit currents will be 60 / 32 / 18 mA (max) respectively.

Capacitance ($T_A=25^\circ\text{C}$, $f=1\text{MHz}$) Note: These parameters are calculated, not measured.

Parameter	Symbol	Test Condition	<i>typ</i>	<i>max</i>	Unit
Input Capacitance	$\overline{CS1}\sim\overline{4}$, $\overline{WE1}\sim\overline{4}$	C_{IN1} $V_{IN}=0\text{V}$	-	16	pF
	Other Inputs	C_{IN2} $V_{IN}=0\text{V}$	-	34	pF
Output Capacitance	32 bit	C_{OUT32} $V_{OUT}=0\text{V}$	-	22	pF

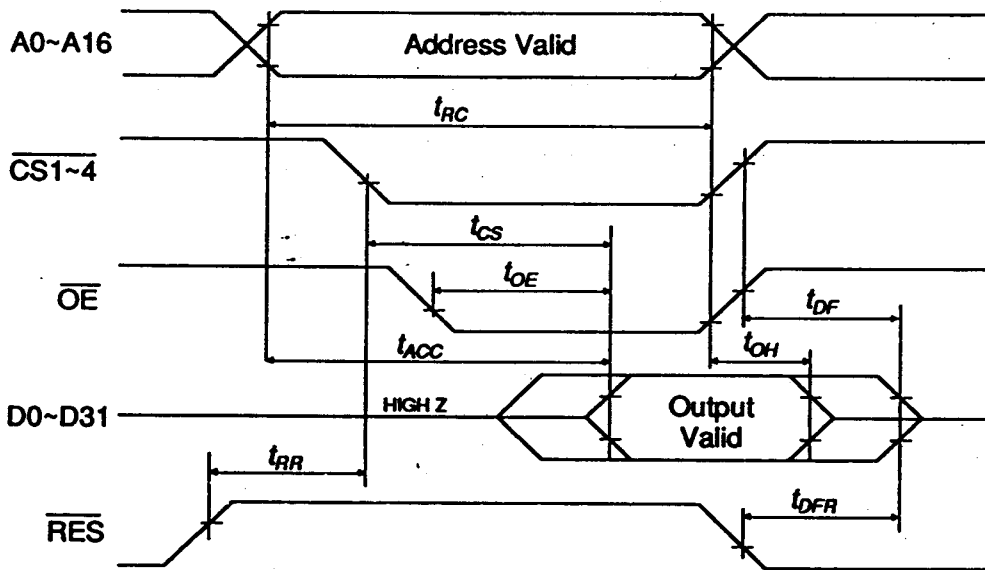
AC READ CHARACTERISTICS

Read Cycle

Parameter	Symbol	-12 ⁽³⁾		-15		-20		Unit
		min	max	min	max	min	max	
Address to Output Delay	t_{ACC}	-	120	-	150	-	200	ns
Chip Select to Output Delay	t_{CS}	-	120	-	150	-	200	ns
Output Enable to Output Delay	t_{OE}	10	60	10	75	10	80	ns
Address to Output Hold	t_{OH}	0	-	-	-	0	-	ns
Output Enable to Output Float	$t_{DF}^{(1)}$	0	45	0	50	0	55	ns
	$t_{DFR}^{(2)}$	0	350	0	350	0	350	ns
Reset to Output Delay	$t_{RR}^{(2)}$	0	600	0	600	0	600	ns

Notes: (1) t_{DF} is defined as the time at which the output achieves the open circuit condition and is not referenced to output voltage levels. This parameter is guaranteed and not 100% tested.
 (2) These parameters are not tested but guaranteed by design.
 (3) Available over commercial temperature range only.

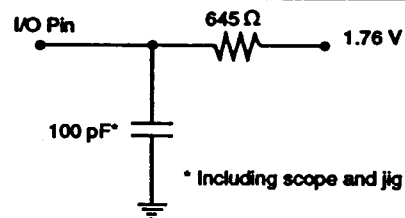
Read Cycle Timing Waveform



AC Test Conditions

- * Input pulse levels: 0.0V to 3.0V
- * Input rise and fall times: 5ns
- * Input and Output timing reference levels: 1.5V
- * $V_{cc} = 5V \pm 10\%$
- * Module tested in 32 bit mode.

Output Load



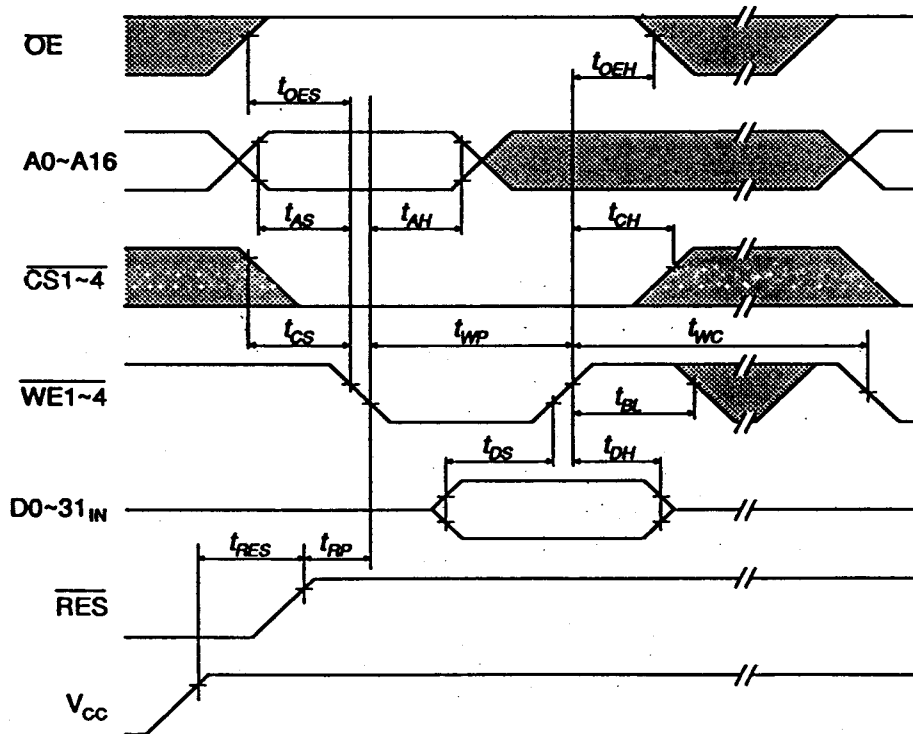
AC WRITE CHARACTERISTICS - BYTE AND PAGE

Write Cycle

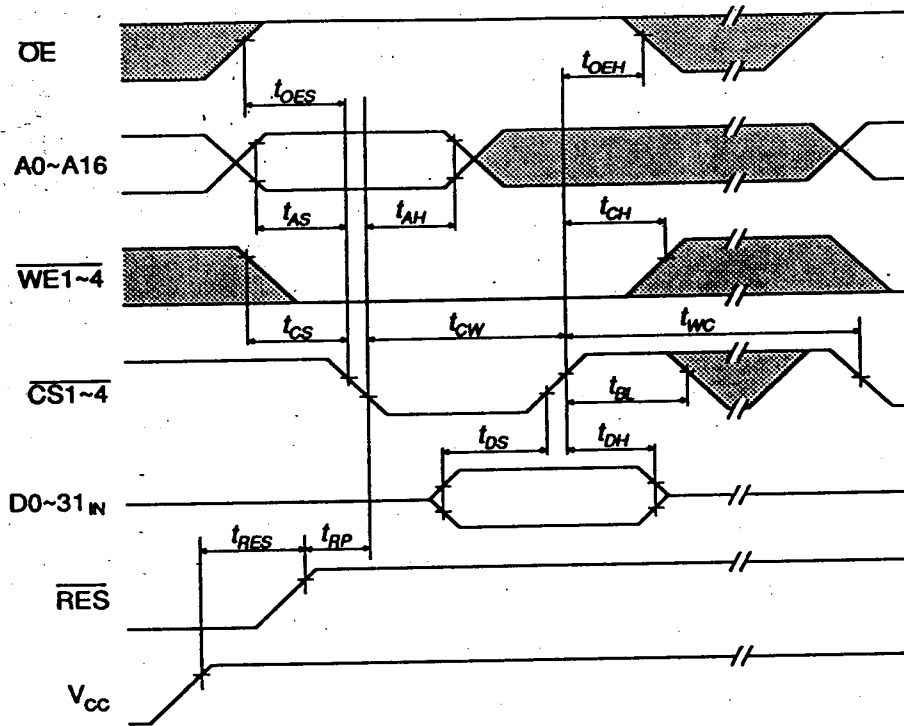
Parameter	Symbol	min	typ	max	Unit
Address Set-up Time	t_{AS}	0	-	-	ns
Chip Select Set-up Time	t_{CS}	0	-	-	ns
Write Pulse Width	t_{WP}	150	-	-	ns
	t_{CW}	150	-	-	ns
Address Hold Time	t_{AH}	150	-	-	ns
Data Set-up Time	t_{DS}	100	-	-	ns
Data Hold Time	t_{DH}	0	-	-	ns
Chip Select Hold Time	t_{CH}	0	-	-	ns
Output Enable Set-up Time	t_{OES}	0	-	-	ns
Output Enable Hold Time	t_{OEH}	0	-	-	ns
Data Latch Time	t_{DL}	200	-	-	ns
Write Cycle Time	t_{WC}	-	-	10	ms
Byte Load Window	t_{BL}	100	-	-	μ s
Byte Load Cycle	t_{BLC}	0.35	-	30	μ s
Reset to Write Set-up Time	t_{RP}	100	-	-	μ s
V_{CC} to Reset Set-up Time	t_{RES}	1	-	-	μ s

Note: (1) Normal writing is not possible when the \overline{RES} terminal becomes low during writing. The \overline{RES} terminal should not be made low for at least 10ms after the last writing pulse is input.

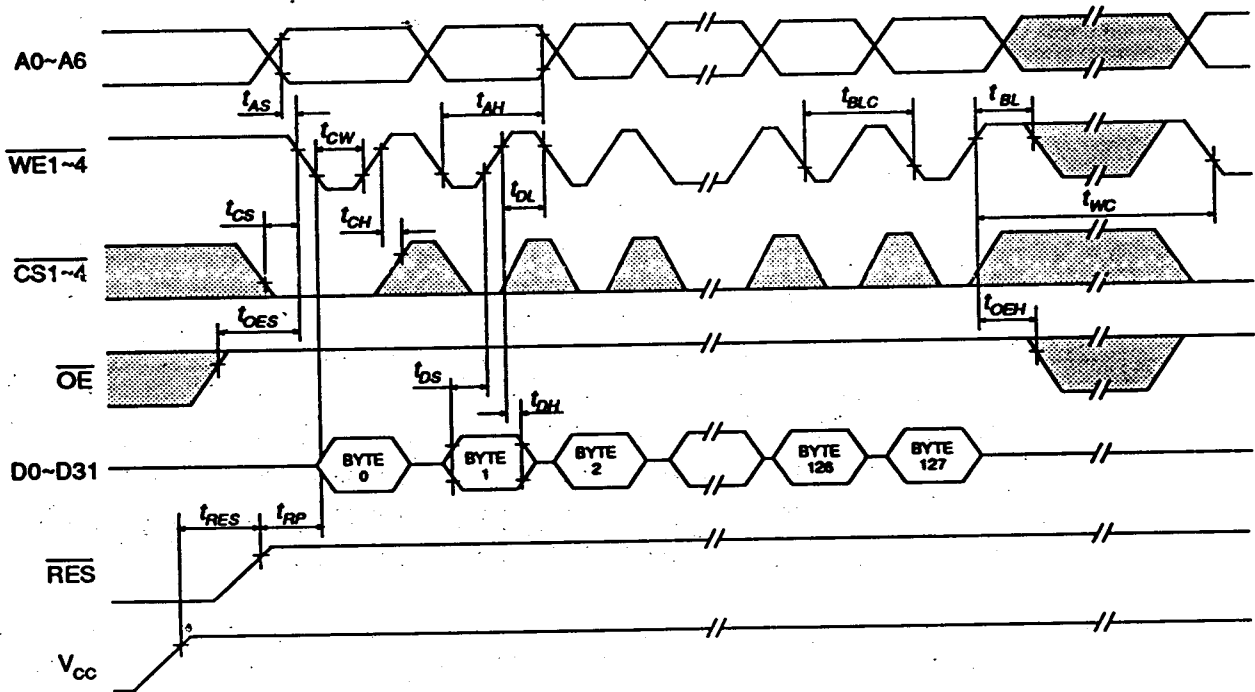
AC Write Waveform - WE Controlled



AC Write Waveform - CS Controlled

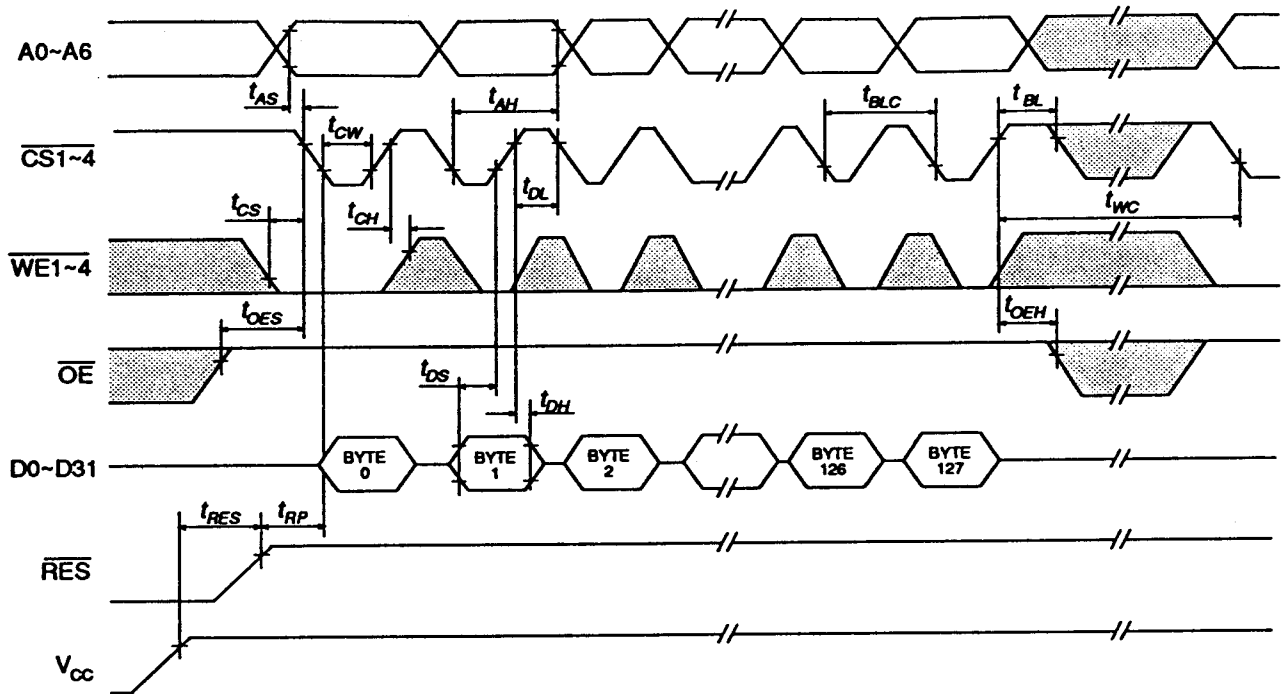


Page Mode Write Waveform - WE Controlled



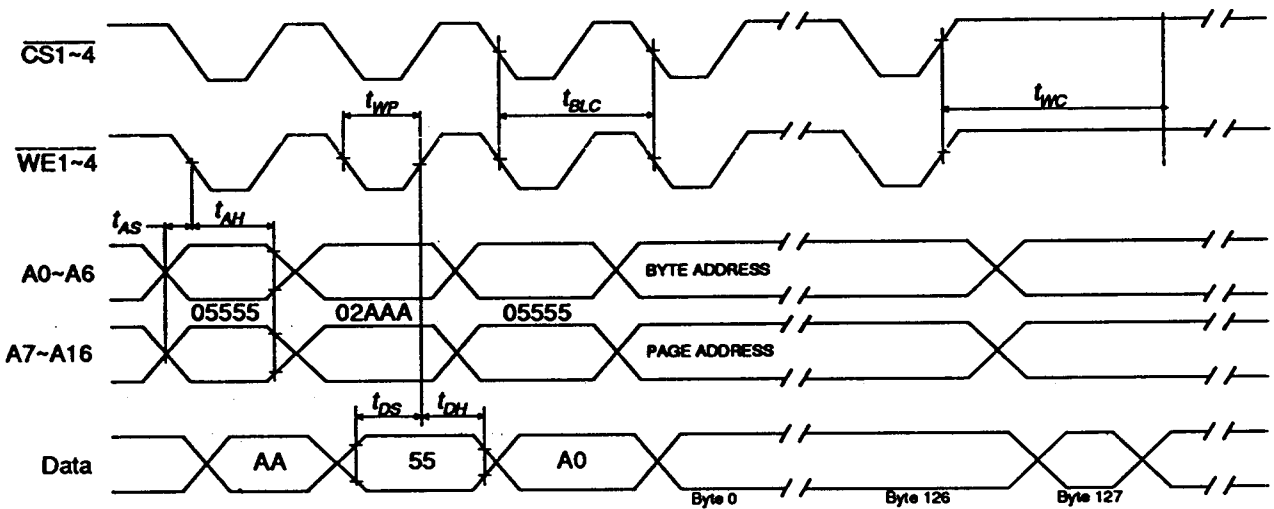
Note: A7 through A16 must specify the page address during each high to low transition of WE (or CS).

Page Mode Write Waveform - CS Controlled



Note: A7 through A16 must specify the page address during each high to low transition of \overline{WE} (or \overline{CS}).

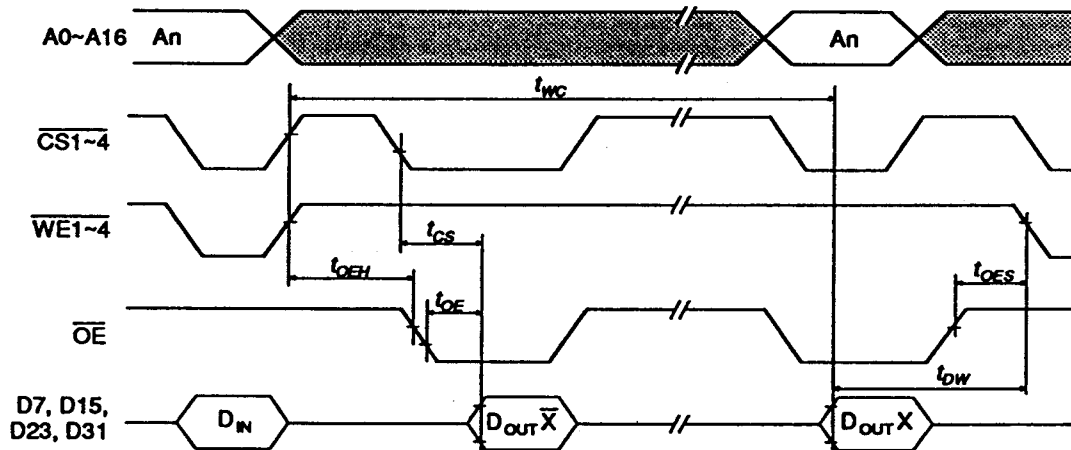
Software Protected Write Waveform



- Notes: (1) A7 through A15 must specify the page address during each high to low transition of \overline{WE} (or \overline{CS})
- (2) The example above is for the PUMA 3E4000X module operating in 8 bit mode.

DATA Polling Characteristics

Parameter	Symbol	min	typ	max	Unit
Output Enable Hold Time	t_{OEH}	0	-	-	ns
Output Enable Set-up Time	t_{OES}	0	-	-	ns
Write Start Time	t_{DW}	150	-	-	ns
Write Cycle Time	t_{WC}	-	-	10	ms

DATA Polling Waveform

DEVICE OPERATION

Read

The PUMA 3E4000X is accessed in the same way as a static RAM, with the data stored at the memory location determined by the address pins being placed on the output pins when CS1~4 and OE are low, and WE1~4 are high. Whenever CS1~4 or OE are high, the outputs are in the OFF or high impedance state.

Write

A low pulse on WE1~4 with CS1~4 low or a low pulse on CS1~4 with WE1~4 low indicates a write cycle. The address is latched on the falling edge of CS1~4 or WE1~4, and the data is latched on the first rising edge of CS1~4 or WE1~4. Once a byte write has begun it will automatically time itself to completion.

Page Mode Write

This operation mode allows 1 to 128 bytes of data to be loaded into a device, which are then simultaneously written. Once the first byte has been written, each subsequent byte must have the high to low transition of WE1~4 (or CS1~4) within 30µs of the same transition of the previous byte. If CS1~4 and WE1~4 are held high for 100µs after a byte has been loaded, the loaded bytes are automatically written. A7 to A16 specify the page address (which must be valid during the above transitions) and A0 to A6 specify which bytes within the page are to be written. Note that the bytes may be loaded in any order and may be changed within the same load period.

DATA Polling

In order to detect the end of a Write Cycle, DATA Polling is provided. During a Write operation (Byte or Page) an attempt to read the last byte written will result in the complement of the written data appearing on D7 (or D15, D23 or D31, depending on the device selected). Once the Write Cycle is complete, true data appears on the outputs and the next Write Cycle may begin. Using this method of indicating the end of a Write can effectively halve the total write time.

Write Cycle Endurance

Each device used on the PUMA 3E4000X is able to withstand at least 10⁵ Write/Erase cycles when used in Page Mode, and at least 10⁴ such cycles when used in Byte Mode.

Data Protection

Both hardware and software protection is provided as described below.

Four types of hardware protection give high security against accidental writes:

- (a) If RES is kept low, no devices on the PUMA 3E4000X can be Erased or Programmed, so data can be protected while V_{cc} is switched.
- (b) OE low, CS1~4 or WE1~4 high inhibits inadvertent Write Cycles during power-on and power-off. Write Cycle timing specifications must be observed concurrently.
- (c) Pulses of less than 20ns on WE1~4 do not initiate a Write Cycle.
- (d) If V_{cc} ≤ 3.0V, Write is inhibited

Software controlled data protection, once enabled by the user, means that a software algorithm must be used before any write can be performed. To enable this feature the algorithm on page 9 is followed, and must be reused for each subsequent write operation. Once set the data protection remains operational until it is disabled by the using the second algorithm; power transitions will not reset this feature.

Operating Modes

The table below shows the logic inputs required to control the operating modes of each EEPROM on the PUMA 3E4000X. Note that CS and WE below are accessed by CS1~4 and WE1~4 respectively to allow 8, 16 and 32 bit operation.

*Further operating information can be found in the EEPROM application notes available from MSI.

MODE	CS	OE	WE	RES	Outputs
Standby	1	X	X	X	High Z
Read	0	0	1	V _H	D _{OUT}
Write	0	1	0	V _H	D _{IN}
Deselect	0	1	1	V _H	High Z
Write Inhibit	X	X	1	X	
	X	0	X	X	
Data Polling	0	0	1	V _H	D _{OUT} (D7)
Program	X	X	X	0	High Z

1 = V_H

0 = V_L

V_H = V_{cc}-1.0V to V_{cc}+1.0V

X = Don't care

Software Data Protection

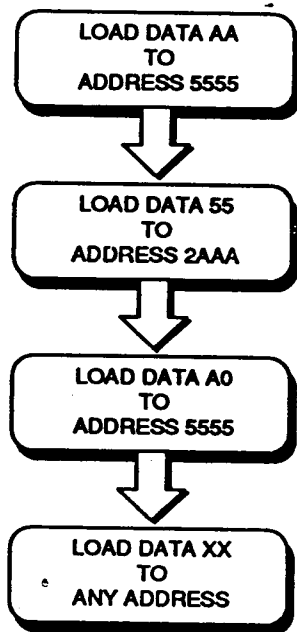
The algorithms below describe the process by which an individual 128K x 8 device on the PUMA may be software write protected and unprotected. Thus, these algorithms apply to the PUMA operating in 8 bit mode; if 16 or 32 bit modes are being used, then the relevant data would be placed on the 16 or 32 bit buses as two or four 8 bit bytes respectively e.g. 5555_H and 55555555_H. In the case of 16 bit mode, this process would be repeated twice with the appropriate devices selected.

The PUMA 3E4000X is shipped with data Protection **NOT ENABLED**. In this mode data should be protected during power-up and power-down operations through the use of external circuits.

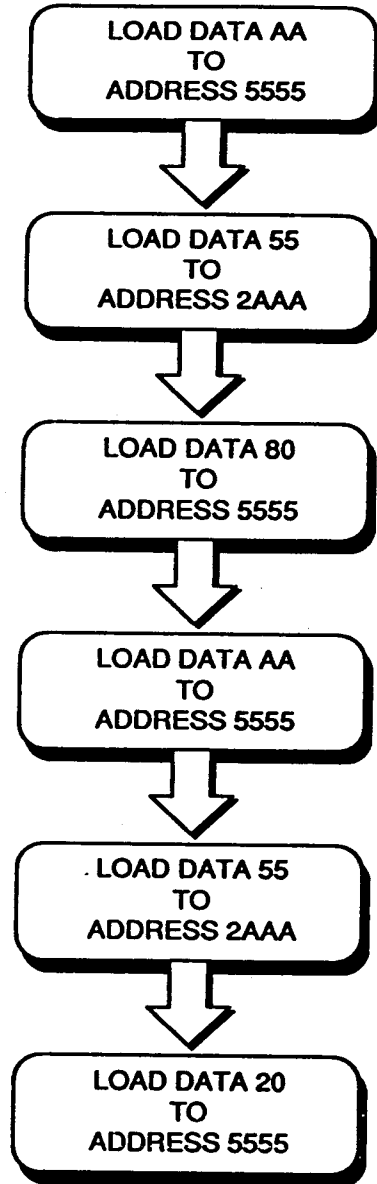
Once data protection has been enabled it is set for the life of the device unless the reset algorithm is followed. In protected mode write operations to the device(s) on the PUMA must be preceded by a series of three write operations to three specific locations, after which 1 to 128 bytes of data may be written. Once the page load cycle is complete, the device(s) return to the data protected state.

NOTE: Once Initiated, the sequence of write operations to Enable and Disable Write Protect should not be Interrupted.

Enable Algorithm⁽¹⁾⁽⁴⁾⁽²⁾



Disable Algorithm⁽¹⁾

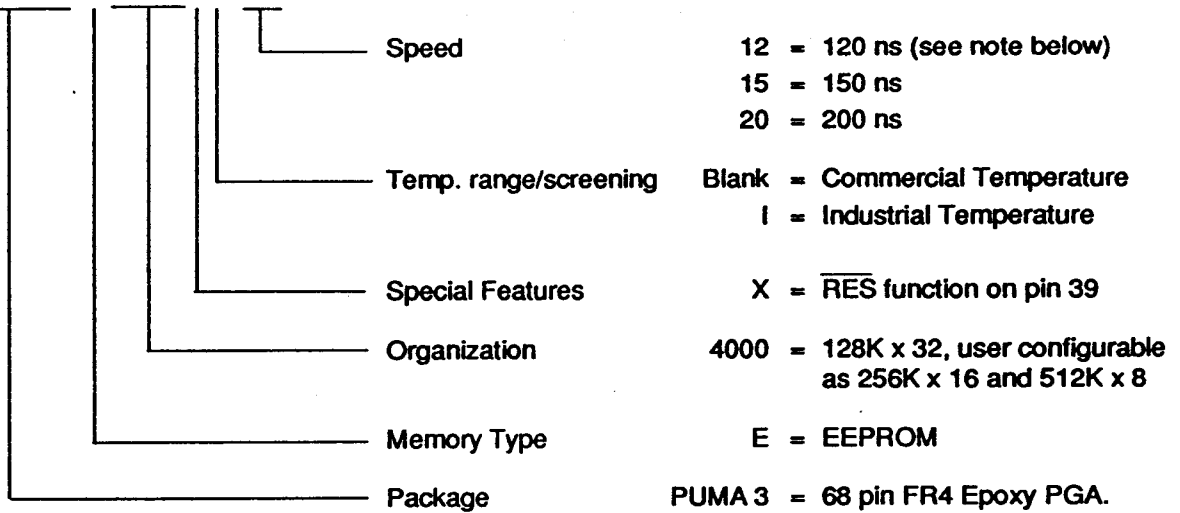


Notes:

- (1) Data Format I/O7-I/O0 (Hex);
Once Initiated, this sequence of write operations should not be interrupted.
- (2) Enable Write Protect state will be initiated at end of write even if no other data is loaded.
- (3) 1 to 128 bytes of data may be loaded.

Ordering Information

PUMA 3E4000XI-15



NOTE : THE 120 ns MODULE IS AVAILABLE OVER THE COMMERCIAL TEMPERATURE RANGE ONLY.



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